WHAT IS CLAIMED IS:

1. An image display having an electromagnetic shield comprising a conductive material with an irregular network structure.

2. The image display of claim 1, wherein said network structure comprises thin lines having a width of 10 nm to 10 μm.

3. A method for producing an image display having an electromagnetic shield, comprising the steps of forming a thin film on a substrate; generating microcracks in a network manner in said thin film; and filling said microcracks with a conductive material to form said electromagnetic shield.

4. A method for producing an image display having an electromagnetic shield, comprising the steps of forming an underlayer on a substrate; forming a thin film on said underlayer; generating microcracks in a network manner in said thin film; activating portions of said underlayer exposed to said microcracks; removing said thin film; and depositing or bonding a conductive material only onto the activated portions of said underlayer to form said electromagnetic shield.

5. The method of claim 3, wherein said thin film is (1) a sol-gel film obtained by applying a sol-gel liquid, (2) a fine-particle film obtained by applying a liquid containing fine particles, or (3) a vapor deposition film obtained by depositing a vaporized thin-film-forming material; and wherein said microcracks are generated by drying said sol-gel film or said fine-particle film, or by accumulating stress in said vapor deposition film during its growth.

6. The method of claim 4, wherein said thin film is (1) a sol-gel film obtained by applying a sol-gel liquid, (2) a fine-particle film obtained by applying a liquid containing fine particles, or (3) a vapor deposition film obtained by depositing a vaporized thin-film-forming material; and wherein

said microcracks are generated by drying said sol-gel film or said fine-particle film or by accumulating stress in said vapor deposition film during its growth.

7. The method of claim 3, comprising the steps of forming said thin film after forming an underlayer by plating on said substrate; generating microcracks in a network manner in said thin film; and depositing said conductive material on portions of said plated underlayer exposed to said microcracks by plating to form said electromagnetic shield.

8. The method of claim 4, comprising the steps of forming said thin film after forming an underlayer by plating on said substrate; generating microcracks in a network manner in said thin film; activating portions of said plated underlayer exposed to said microcracks, and depositing said conductive material to the activated portions of said plated underlayer by plating to form said electromagnetic shield.

9. The method of claim 7, wherein said plating is electroless plating; and wherein said plated underlayer comprises a plating catalyst or its precursor.

10. The method of claim 8, wherein said plating is electroless plating; and wherein said plated underlayer comprises a plating catalyst or its precursor.

11. The method of claim 3, comprising the steps of forming said thin film after forming a bondable underlayer having bondability to said conductive material or acquiring bondability to said conductive material by activation on said substrate; generating microcracks in a network manner in said thin film; and bonding particles of said conductive material to portions of said bondable underlayer exposed to said microcracks.

12. The method of claim 4, comprising the steps of forming said thin film after forming a bondable underlayer having bondability to said

conductive material or acquiring bondability to said conductive material by activation on said substrate; generating microcracks in a network manner in said thin film; activating portions of said bondable underlayer exposed to said microcracks; and bonding particles of said conductive material to the activated portions of said bondable underlayer.

13. The method of claim 11, wherein said bondable underlayer has a functional group bondable to said conductive material or a functional group acquiring bondability to said conductive material by activation.

14. The method of claim 12, wherein said bondable underlayer has a functional group bondable to said conductive material or a functional group acquiring bondability to said conductive material by activation.